# DEL-00057-N1-GP

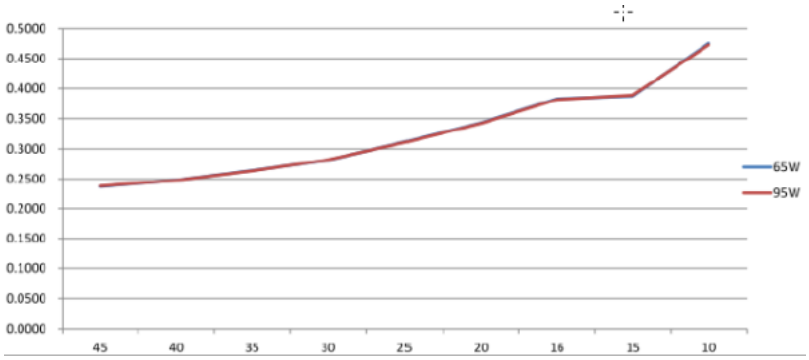
## Thermal and Mechanical Spec

Thermal performance for 65W/95W CPU

HSK Assembly Weight: 196.56g

CPU Loading: 65 lbf

## Performance Curve



## Application

LGA 2011 (Socket R Narrow)

Test result:

| | 65W | 95W |
|---|---|---|
| Flow (CFM) | Rca (℃/W) | Rca (℃/W) |
| 10 | 0.4751 | 0.4725 |
| 15 | 0.3872 | 0.3887 |
| 16 | 0.3829 | 0.3814 |
| 20 | 0.3431 | 0.3421 |
| 25 | 0.3116 | 0.3104 |
| 30 | 0.2815 | 0.2821 |
| 35 | 0.2643 | 0.2635 |
| 40 | 0.2481 | 0.2478 |
| 45 | 0.2376 | 0.2383 |

## Component Specifications

| | |
|---|---|
| Application System | 1U+ Form Factor Passive Solution |
| Material | Aluminum Extrusion |
| Dimension | 106L x 70W x 26.5H mm |
| Fin | Thick= 1.20mm , Pitch= 2.60mm , 17 fin |
| Thermal interface Material | ShinEstu 7783 ( 38.5 x 38mm ) |

*All readings are typical values at rated voltage.

*Specifications are subjected to change without notice.

## Safety